

## **Supplementary Materials for**

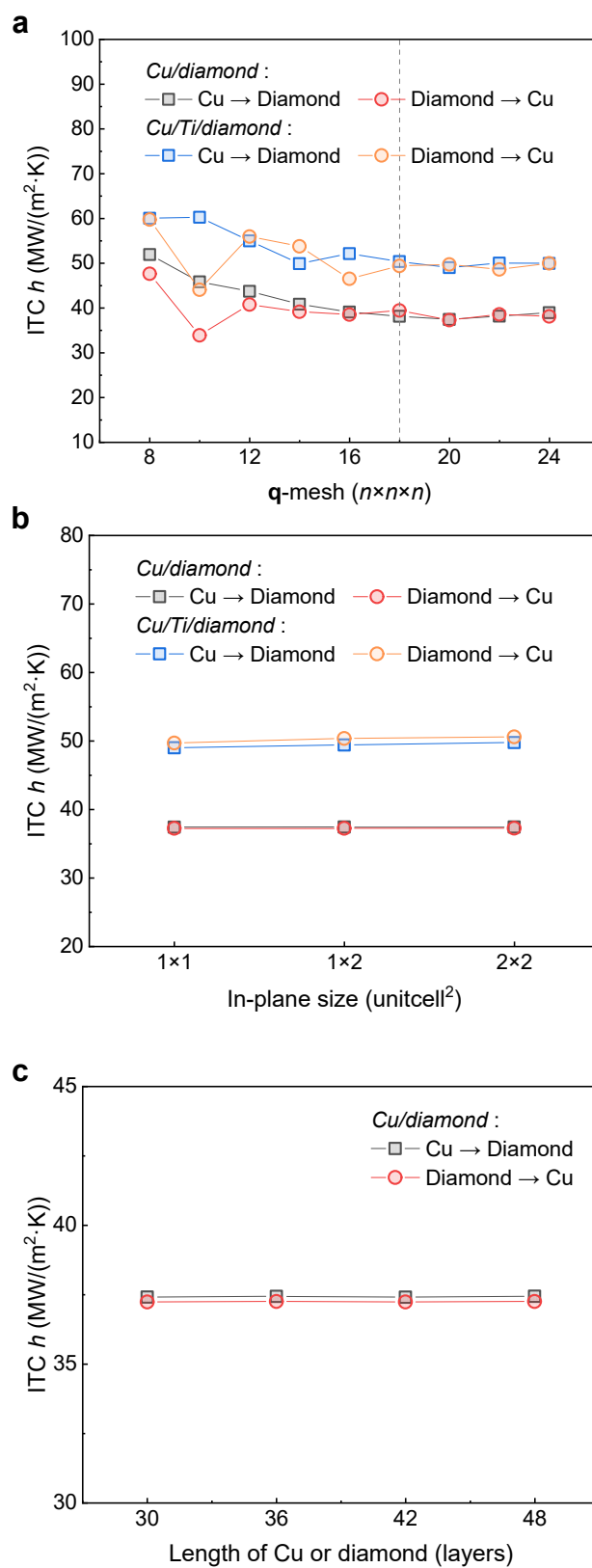
**“Role of modification interlayers in enhancing thermal transport  
across metal/diamond interfaces”**

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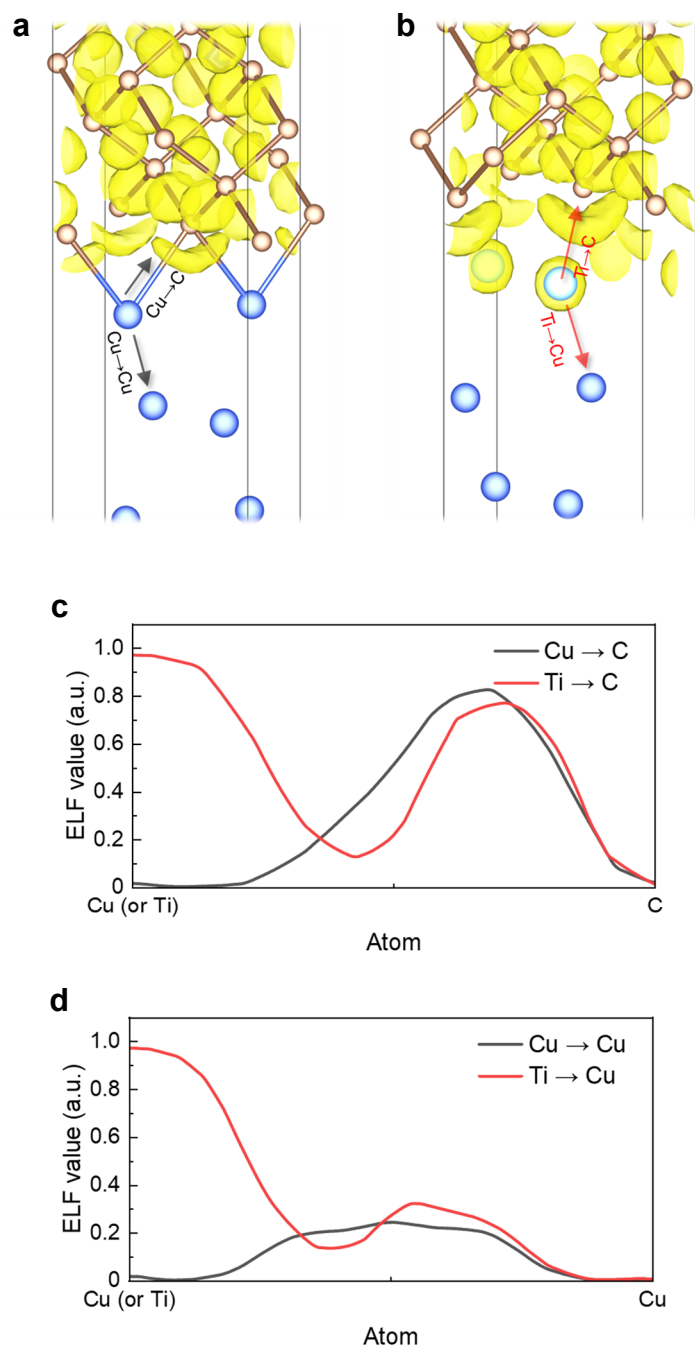
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## Supplementary Figures



**Figure S1.** Convergence tests of lattice dynamics simulations against (a)  $q$ -mesh of the 1<sup>st</sup> Brillouin zone, (b) in-plane sizes of models, (c) total lengths of models.



**Figure S2.** Analyses on the electron localization function (ELF). The ELF isosurfaces at 0.75 of (a) the Cu/diamond interface and (b) the Cu/Ti/diamond interface. There exist lone pairs of electrons around Ti atoms. ELF profiles along (c) Cu → C, Ti → C interactions, (d) Cu → Cu, Ti → Cu interactions.